



FOR IMMEDIATE RELEASE

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Enerdyne Solutions and Indium Corporation of America Sign Agreement

NORTH BEND, WA. May 29, 2007 – Indium Corporation and Enerdyne Solutions today announced plans to collaborate their efforts in manufacturing, selling, and supporting Enerdyne Solutions’ unique Indigo™ metal thermal interface material (mTIM) to the electronics manufacturing industry. Their memorandum of understanding provides a roadmap and terms of additional agreements that build on proven laboratory results, customer evaluations, and the companies’ ongoing relationship. Further terms were not disclosed.

The Indigo™ mTIM solves the critical problem of removing excess heat from electronic components. It provides more than twice the performance of the best available thermal greases and poly-solder hybrids in use today. The combination of superior cooling and modest cost makes the Indigo™ mTIM an ideal solution for critical applications including chip packaging in desktop computers, servers, workstations, game consoles, and other devices.

Enerdyne President Chris Leyerle noted that both companies are experienced with the thermal management industry and the competitive landscape, and are both bringing significant intellectual property and potential customers to the relationship. “We are enormously pleased to be working with Indium,” commented Leyerle. “Their expertise in metals and high-volume manufacturing, and their position as the world’s leader in metal-based TIMs, make them an ideal partner in realizing the enormous market potential of this product.”

Ross Berntson, Indium Corporation’s Solder Products Business Unit Vice President said, “Enerdyne’s Indigo™ metal TIM is a world-class product. It fits perfectly into Indium Corporation’s manufacturing capabilities as well as into our product suite. Customers expect leading-edge products and performance from Indium. Indigo™ mTIM compliments this perfectly.”

Heat is fatal to electronics performance, and the problem of mitigating that heat is an increasingly disruptive and expensive problem for the electronics industry. The problem has become more acute primarily as a result of the increasing miniaturization of electronics and the competitive advantages of denser packaging. Efforts to reduce power consumption have not kept pace, and the result is a relentless increase in heat flux density (the ratio of heat dissipation to unit area).

Enerdyne Solutions develops and commercializes electronics cooling products and technologies. The Company has used its multi-disciplinary scientific expertise and experience to generate multiple patents and thermal products characterized by higher performance at reduced cost, as well as enabling overall solutions that are lighter, smaller, and quieter. Products include the

Cool solutions for hot problems



ENERDYNE SOLUTIONS

Indigo™ thermal interface material, Polara™ heat spreaders, a Peltier-assisted semiconductor technology ideal for hot spot mitigation; and PermaFrost™ thermoelectric devices, well-suited for solid-state cooling, heating, and power generation. For more information on Enerdyne Solutions visit www.enerdynesolutions.com or email info@enerdynesolutions.com.

Indium Corporation is a four-time Frost & Sullivan Award-winning supplier of electronics assembly materials, including solder pastes, solder preforms, fluxes, Pb-Free solder alloys, underfill materials, die-attach materials, thermal interface materials, and more. The company is also the world's premiere supplier of commercial grade and high-purity indium. Factories are located in the USA, the United Kingdom, Singapore, and China. Founded in 1934, the company is ISO 9001 registered. For more information on Indium Corporation visit www.indium.com or email askus@indium.com.

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